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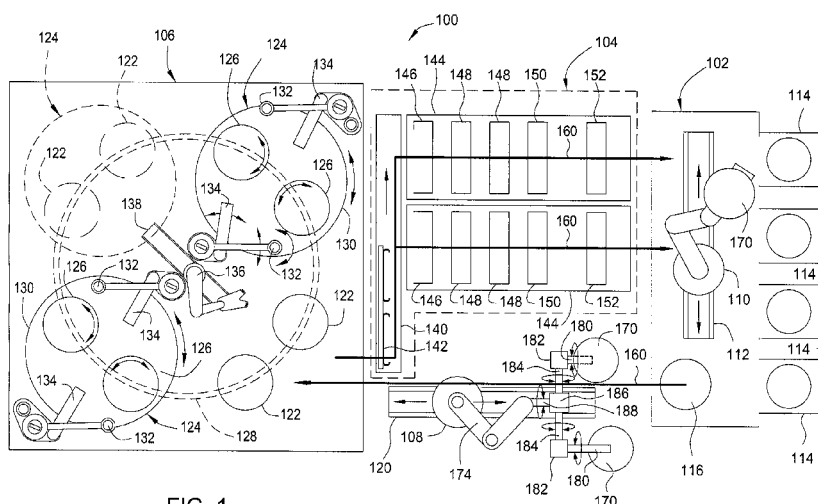


FIG. 1

(57) Abstract: Embodiments of a system and method for polishing substrates are provided. In one embodiment, a polishing system is provided that includes a polishing module, a cleaner and a robot. The robot has a range of motion sufficient to transfer substrates between the polishing module and cleaner. The polishing module includes at least two polishing stations, at least one load cup and at least four polishing heads. The polishing heads are configured to move independently between the at least two polishing stations and the at least one load cup.